PACKAGE DIMENSIONS						
CA	FP-1, EXPOSED ASE 127FG ISSUE O	DBC			DATE 12	IUL 2022
PIN 1 Identifier 2D Code Marking Area TOP VIEW $\oplus 0000 C A B$ NOTE 3 NOTE 4	1 2 3 4 ØF 5 6	4. POSITION OF ROOT OF THE 5. PIN 1 IDENTIF 3. MISSING PINS 7. L1 IS THE STR DIN A	, 2009. 3 DIMENSIG and c APPL ED BETWE ETHE LEAD WHI I LEAD WHI I CATION IS ARE 3,4,7, AIGHT POF MILL MIN. 5.30 3.00	DN: MILLIM   Y TO THE   EN 1.00 AN   IS DETERM   RETERMERE IT EXIT   A MIRROR   8,11,12,14   RTION OF T   IMETERS   NOM.   5.50   3.20   5.00   0.60   0.50	ETERS PLATED LEADS ID 2.00 FROM T IINED AT THE IS THE PACKA IED SURFACE AND 15.	THE LEAD TIP GE BODY. NDENT.
FRONT VIEW	G	D1 E E F L L1 M M	20.40 12.75 3.10 6.30 3.23	20.90 13.25 1.27 BSC 3.60 6.80 3.73 33.9 REF 17.4 REF ERIC	41.50 21.40 13.75 4.10 7.30 4.23	
BOTTOM VIEW EXPOSED DBC		XXXX = S ZZZ = A AT = A Y = Y	Specific D Specific D Sssembly Vork Wee	AXXXXXX AXXXXX AXXXXX AXXXX AXXXXX AXXXXXX	ode e	
DOCUMENT NUMBER: 98AON47384H DESCRIPTION: SIP29 44x20.9 FP-1, EXPO	Electronic versions are unco Printed versions are uncontr		sheet for cator, "G e present e Generic hen accesse	actual p or micro Some p Marking d directly fro	part marking podot "•", ma products ma om the Docume ED COPY" in rec	J. Y Y nt Repository.
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**MECHANICAL CASE OUTLINE** 

PACKAGE DIMENSIONS

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